Notice for TAIYO YUDEN products

Please read this notice before using the TAIYO YUDEN products.

REMINDERS

Product information in this catalog is as of October 2010. All of the contents specified herein are subject to change without notice due to technical improvements, etc. Therefore, please check for the latest information carefully before practical application or usage of the Products.

Please note that Taiyo Yuden Co., Ltd. shall not be responsible for any defects in products or equipment incorporating such products, which are caused under the conditions other than those specified in this catalog or individual specification.

- Please contact Taiyo Yuden Co., Ltd. for further details of product specifications as the individual specification is available.
- Please conduct validation and verification of products in actual condition of mounting and operating environment before commercial shipment of the equipment.
- All electronic components or functional modules listed in this catalog are developed, designed and intended for use in general electronics equipment.(for AV, office automation, household, office supply, information service, telecommunications, (such as mobile phone or PC) etc.). Before incorporating the components or devices into any equipment in the field such as transportation,(automotive control, train control, ship control), transportation signal, disaster prevention, medical, public information network (telephone exchange, base station) etc. which may have direct influence to harm or injure a human body, please contact Taiyo Yuden Co., Ltd. for more detail in advance. Do not incorporate the products into any equipment in fields such as aerospace, aviation, nuclear control, submarine system, military, etc. where higher safety and reliability are especially required.

In addition, even electronic components or functional modules that are used for the general electronic equipment, if the equipment or the electric circuit require high safety or reliability function or performances, a sufficient reliability evaluation check for safety shall be performed before commercial shipment and moreover, due consideration to install a protective circuit is strongly recommended at customer's design stage.

- The contents of this catalog are applicable to the products which are purchased from our sales offices or distributors (so called "TAIYO YUDEN's official sales channel").

 It is only applicable to the products purchased from any of TAIYO YUDEN's official sales channel.
- Please note that Taiyo Yuden Co., Ltd. shall have no responsibility for any controversies or disputes that may occur in connection with a third party's intellectual property rights and other related rights arising from your usage of products in this catalog. Taiyo Yuden Co., Ltd. grants no license for such rights.
- Caution for export

Certain items in this catalog may require specific procedures for export according to "Foreign Exchange and Foreign Trade Control Law" of Japan, "U.S. Export Administration Regulations", and other applicable regulations. Should you have any question or inquiry on this matter, please contact our sales staff.

RECTANGULAR FERRITE CHIP BEADS (HIGH CURRENT FB SERIES M TYPE)



WAVE

REFLOW

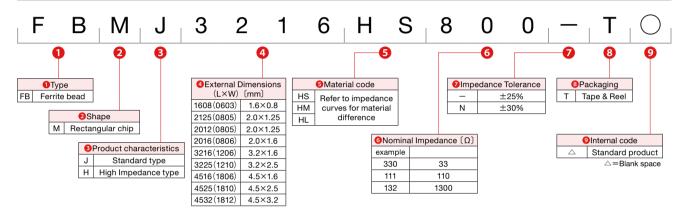
FEATURES

- Power supply units:
- ·Withstand large current (allowable current: up to 6A)
- · Resistance to high energy
- · High reliability
- There are several variations of the FBMJ type
 - HS: For broadband applications
 - HM: For upper MHz range applications
 - HL: For GHz range applications
- The FBMH type is optimal for circuit designs which require high impedances and large currents to combat radiated noise on power lines,

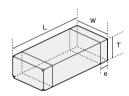
APPLICATIONS

- Deals with power line radiated and conducted noise.
- Provides waveform correction of digital signals and high frequency noise countermeasures in various types of digital equipment.
- Automotive
- Computer Peripherals
- Differential transmission line on USB and similar products
- Mobile devices which require lower power consumption

ORDERING CODE



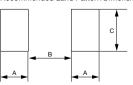
EXTERNAL DIMENSIONS/STANDARD QUANTITY



Tuna	,	w	т	_	Standard Qu	uantity [pcs]
Type	L	VV		е	Paper Tape	Embossed Tape
FBMJ1608	1.6±0.2	0.8±0.2	0.8±0.2	0.3±0.2	4000	
(0603)	(0.063 ± 0.008)	(0.031±0.008)	(0.031±0.008)	(0.012±0.008)	4000	_
FBMJ2125	2.0±0.2	1.25±0.2	0.85±0.2	0.5±0.3	4000	
(0805)	(0.079 ± 0.008)	(0.049 ± 0.008)	(0.033±0.008)	(0.020±0.012)	4000	_
FBMJ3216	3.2±0.3	1.6±0.2	1.1±0.2	0.5±0.3		2000
(1206)	(0.126 ± 0.012)	(0.063±0.008)	(0.043±0.008)	(0.020±0.012)	_	2000
FBMJ4516	4.5±0.3	1.6±0.2	1.1±0.2	0.5±0.3		2000
(1806)	(0.177 ± 0.012)	(0.063±0.008)	(0.043±0.008)	(0.020±0.012)	_	2000
FBMH1608	1.6±0.1	0.8±0.1	0.8±0.1	0.3±0.15	4000	_
(0603)	(0.063 ± 0.004)	(0.031±0.004)	(0.031±0.004)	(0.012±0.006)	4000	
FBMH2012	2.0±0.2	1.25±0.2	0.85±0.2	0.5±0.3	4000	_
(0805)	(0.079 ± 0.008)	(0.049 ± 0.008)	(0.033±0.008)	(0.020±0.012)		_
FBMH2016	2.0±0.2	1.6±0.2	1.6±0.2	0.5±0.3	_	2000
(0806)	(0.079 ± 0.008)	(0.063±0.008)	(0.063±0.008)	(0.020±0.012)	_	2000
FBMH3216	3.2±0.3	1.6±0.2	1.6±0.2	0.5±0.3		2000
(1206)	(0.126 ± 0.012)	(0.063±0.008)	(0.063±0.008)	(0.020±0.012)	_	2000
FBMH3225	3.2±0.3	2.5±0.3	2.5±0.3	0.5±0.3		1000
(1210)	(0.126 ± 0.012)	(0.098±0.012)	(0.098±0.012)	(0.020±0.012)	_	1000
FBMH4516	4.5±0.3	1.6±0.2	1.6±0.2	0.5±0.3	_	2000
(1806)	(0.177±0.012)	(0.063±0.008)	(0.063±0.008)	(0.020±0.012)	_	2000
FBMH4525	4.5±0.4	2.5±0.3	2.5±0.3	0.9±0.6		1000
(1810)	(0.177±0.016)	(0.098±0.012)	(0.098±0.012)	(0.035±0.024)		1000
FBMH4532	4.5±0.4	3.2±0.3	3.2±0.3	0.9±0.6	_	2000
(1812)	(0.177±0.016)	(0.126±0.012)	(0.126±0.012)	(0.035±0.024)	_	2000

Unit: mm(inch)

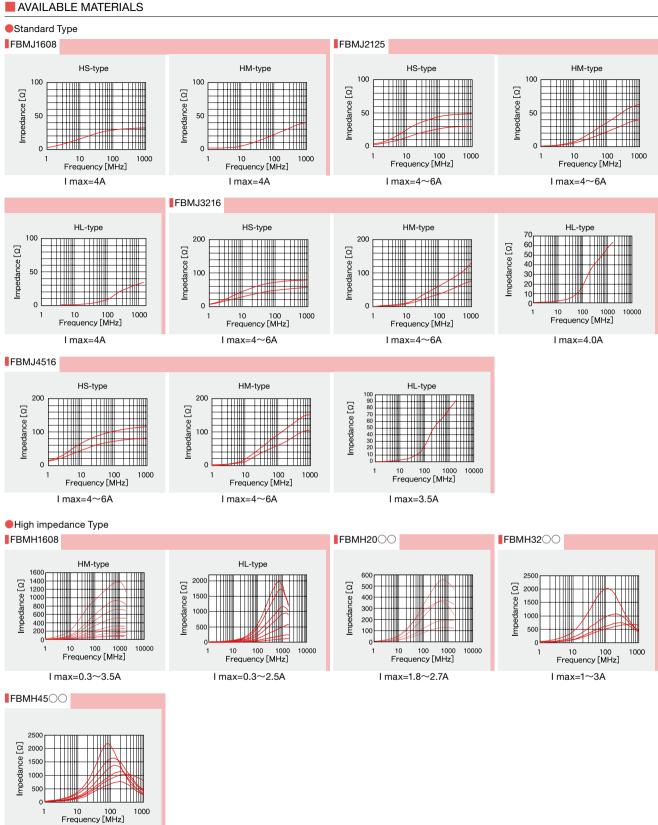
Recommended Land Pattern Dimensions



Parts Number	Dimensions (mm)					
Parts Number	Α	В	С			
FB MJ1608 type	1.0	1.0	1.0			
FB MJ2125 type	1.4	1.2	1.65			
FB MJ3216 type	1.4	2.2	2.0			
FB MJ4516 type	1.75	3.5	2.0			
FB MH1608 type	1.0	1.0	1.0			
FB MH2012 type	1.4	1.2	1.65			

Parts Number	Dimensions (mm)				
Parts Number	Α	В	С		
FB MH2016 type	1.4	1.2	2.0		
FB MH3216 type	1.4	2.2	2.0		
FB MH4516 type	1.75	3.5	2.0		
FB MH3225 type	1.4	2.2	2.9		
FB MH4525 type	1.75	3.5	2.9		
FB MH4532 type	1.75	3.5	3.7		

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I max=1.5~4A

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PART NUMBERS

Standard Type

FBMJ1608

Ordering code	EHS (Environmental Hazardous Substances)	Impedance (Ω)	Measuring frequency (MHz)	DC Resistance (Ω) max.	Rated current (A) max.	Thickness (mm) (inch)
FB MJ1608HS280NT	RoHS	28±30%	100	0.007	4.0	0.8±0.2
FB MJ1608HM230NT	RoHS	23±30%	100	100 0.007	4.0	(0.031±0.008)

●FBMJ2125

Ordering code	i i	Environmental Hazardous Substances)	Impedance (Ω)	Measuring frequency (MHz)	DC Resistance (Ω) max.	Rated current (A) max.	Thickness (mm) (inch)
FB MJ2125HS420-T		RoHS	42±25%		0.008	4.0	
FB MJ2125HS250NT		RoHS	25±30%		0.004	6.0	0.05 0.0
FB MJ2125HM330-T		RoHS	33±25%	100	0.008	4.0	0.85±0.2 (0.033±0.008)
FB MJ2125HM210NT		RoHS	21±30%		0.004	6.0	(0.000±0.000)
FB MJ2125HL8R0NT		RoHS	8±30%		0.008	4.0	

●FBMJ3216

Ordering code	EHS (Environmental Hazardous Substances)	Impedance (Ω)	Measuring frequency (MHz)	DC Resistance (Ω) max.	Rated current (A) max.	Thickness (mm) (inch)
FB MJ3216HS800-T	RoHS	80±25%		0.010	4.0	
FB MJ3216HS480NT	RoHS	48±30%		0.005	6.0	
FB MJ3216HM600-T	RoHS	60±25%	100	0.010	4.0	1.1±0.2 (0.043±0.008)
FB MJ3216HM380NT	RoHS	38±30%		0.005	6.0	(0.040±0.000)
FB MJ3216HL160NT	RoHS	16±30%		0.012	4.0	

●FBMJ4516

Ordering code	EHS (Environmental Hazardous Substances)	Impedance (Ω)	Measuring frequency (MHz)	DC Resistance (Ω) max.	Rated current (A) max.	Thickness (mm) (inch)
FB MJ4516HS111-T	RoHS	110±25%		0.014	4.0	
FB MJ4516HS720NT	RoHS	72±30%		0.007	6.0	44100
FB MJ4516HM900-T	RoHS	90±25%	100	0.014	4.0	1.1±0.2 (0.043±0.008)
FB MJ4516HM560NT	RoHS	56±30%		0.007	6.0	(0.040±0.000)
FB MJ4516HL230NT	RoHS	23±30%		0.014	3.5	

High impedance Type

Ordering code	EHS (Environmental Hazardous Substances)	Impedance (Ω)	Measuring frequency (MHz)	DC Resistance (Ω) max.	Rated current (A) max.	Thickness (mm) (inch)
FB MH1608HM470-T	RoHS	47±25%		0.020	3.5	
FB MH1608HM600-T	RoHS	60±25%		0.025	3.0	
FB MH1608HM101-T	RoHS	100±25%		0.035	2.0	
FB MH1608HM151-T	RoHS	150±25%		0.050	2.0	
FB MH1608HM221-T	RoHS	220±25%		0.070	1.5	
FB MH1608HM331-T	RoHS	330±25%		0.130	0.9	
FB MH1608HM471-T	RoHS	470±25%		0.150	0.7]
FB MH1608HM601-T	RoHS	600±25%		0.170	0.7	0.8±0.1
FB MH1608HM102-T	RoHS	1000±25%		0.350	0.5	(0.031±0.004)
FB MH1608HL300-T	RoHS	30±25%		0.028	2.5]
FB MH1608HL600-T	RoHS	60±25%		0.045	1.8	
FB MH1608HL121-T	RoHS	120±25%		0.130	0.9	
FB MH1608HL221-T	RoHS	220±25%		0.170	0.7	
FB MH1608HL331-T	RoHS	330±25%		0.210	0.6	
FB MH1608HL471-T	RoHS	470±25%		0.350	0.5	
FB MH1608HL601-T	RoHS	600±25%	100	0.450	0.4	
FB MH2012HM800-T	RoHS	80±25%		0.025	2.7	
FB MH2012HM121-T	RoHS	120±25%		0.032	2.5	0.85±0.2
FB MH2012HM221-T	RoHS	220±25%		0.060	2.0	(0.033±0.008)
FB MH2012HM331-T	RoHS	330±25%		0.080	1.8	
FB MH2016HM251NT	RoHS	250±30%		0.050	2.0	
FB MH3216HM501NT	RoHS	500±30%		0.070	2.0	1.6±0.2 (0.063±0.008)
FB MH4516HM851NT	RoHS	850±30%		0.100	1.5	(0.003_0.000)
FB MH3225HM601NT	RoHS	600±30%		0.042	3.0	
FB MH3225HM102NT	RoHS	1000±30%		0.100	2.0	05100
FB MH3225HM202NT	RoHS	2000±30%		0.130		2.5±0.3 (0.098±0.012)
FB MH4525HM102NT	RoHS	1000±30%		0.060	3.0	(0.030±0.012)
FB MH4525HM162NT	RoHS	1600±30%		0.130	2.0	
FB MH4532HM681-T	RoHS	680±25%		0.028	4.0	0.01.00
FB MH4532HM132-T	RoHS	1300±25%		0.060	3.0	3.2±0.3 (0.126±0.012)
FB MH4532HM202-T	RoHS	2000±25%		0.130	1.3	(0.120±0.012)

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100 1000 Frequency [MHz]

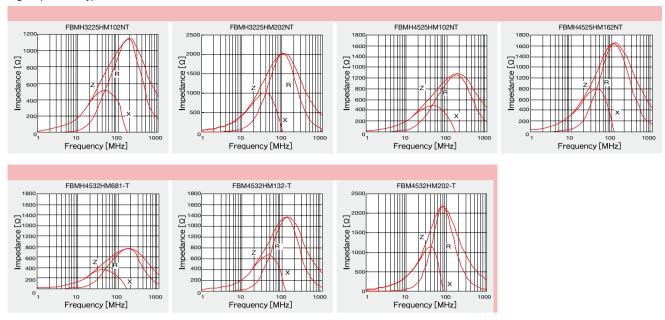
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High impedance Type



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High impedance Type



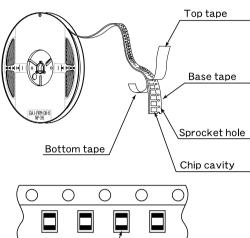
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1Minimum Quantity

Tuna	Standard Qu	antity [pcs]
Туре	Paper Tape	Embossed Tape
1608(0603)	4000	_
2125 (0805)	4000	_
2012 (0805)	4000	_
2016 (0806)	_	2000
3216 (1206)	_	2000
4516 (1806)	_	2000
3225 (1210)	_	1000
4525 (1810)	_	1000
4532 (1812)	_	2000

②Tape Material

Card board carrier tape

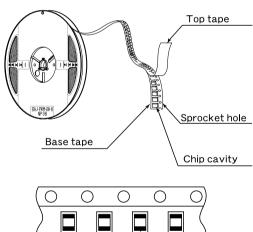


Chip

Embossed Tape

Chip filled

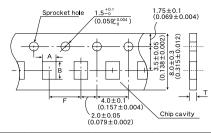
Chip filled



Chip

3 Taping Dimensions

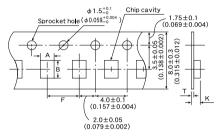
Paper tape (0.315 inches wide)



Type	Chip (Cavity	Insertion Pitch	Tape Thickness
туре	Α	В	-	Т
FBMJ1608 FBMH1608 (0603)	1.0±0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.2 (0.157±0.008)	1.1max (0.043max)
FBMJ2125 FBMH2012 (0805)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.2 (0.157±0.008)	1.1max (0.043max)

Unit : mm (inch)

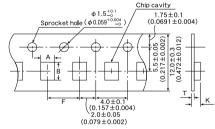
Embossed tape (0.315 inches wide)



Type	Chip	Chip Cavity		Tape Th	ickness
.,,,,,	А	В	F	K	Т
FBMH2016	1.8±0.2	2.2±0.2	4.0±0.2	2.6max	0.6max
(0806)	(0.071±0.008)	(0.087±0.008)	(0.157±0.008)	(0.102max)	(0.024max)
FBMJ3216	1.9±0.2	3.5±0.2	4.0±0.2	1.5max	0.3max
(1206)	(0.075±0.008)	(0.138±0.008)	(0.157±0.008)	(0.059max)	(0.012max)
FBMH3216	1.9±0.2	3.5±0.2	4.0±0.2	2.6max	0.6max
(1206)	(0.075±0.008)	(0.138±0.008)	(0.157±0.008)	(0.102max)	(0.024max)
FBMH3225	2.8±0.2	3.5±0.2	4.0±0.2	4.0max	0.6max
(1210)	(0.110±0.008)	(0.138±0.008)	(0.157±0.008)	(0.157max)	(0.024max)

Unit : mm (inch)

Embossed tape (0.472 inches wide)

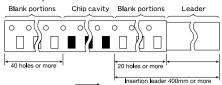


Туре	Chip Cavity		Insertion Pitch	Tape Thickness	
31.	А	В	F	K	Т
FBMJ4516	1.9±0.2	4.9±0.2	4.0±0.2	1.5max	0.3max
(1806)	(0.075±0.008)	(0.193±0.008)	(0.157±0.008)	(0.059max)	(0.012max)
FBMH4516	1.9±0.2	4.9±0.2	4.0±0.2	2.6max	0.6max
(1806)	(0.075±0.008)	(0.193±0.008)	(0.157±0.008)	(0.102max)	(0.024max)
FBMH4525	2.9±0.2	4.9±0.2	4.0±0.2	4.0max	0.6max
(1810)	(0.114±0.008)	(0.193±0.008)	(0.157±0.008)	(0.157max)	(0.024max)
FBMH4532	3.6±0.2	4.9±0.2	8.0±0.2	4.0max	0.6max
(1812)	(0.142±0.008)	(0.193±0.008)	(0.315±0.008)	(0.157max)	(0.024max)

Unit : mm (inch)

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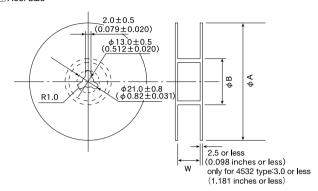
4 Leader and Blank portion



Direction of tape feed

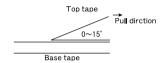
Insertion leader is 400 mm or more (including 20 empty cavities) Empty cavities at end of reel: 40 holes or more

5Reel size



Туре	φA [mm] (inch)	ϕ B [mm] (inch)	W [mm] (inch)
FBMJ1608		180 ⁺⁰ 60 ⁺¹	
FBMJ2125			10.0±1.5 (0.394±0.047)
FBMJ3216			(0.004=0.041)
FBMJ4516			14.0±1.5 (0.551±0.059)
FBMH1608	180+0		10.0±1.5 (0.394±0.047)
FBMH2012	(7.09 ⁺⁰ _{-0.118})	(2.36 ^{+0.039})	
FBMH2016	-0.116		
FBMH3216			
FBMH3225			
FBMH4516			14.0±1.5
FBMH4525			(0.551±0.059)
FBMH4532	330±2.0 (12.99±0.080)	100±1.0 (3.94±0.039)	14±2.0 (0.551±0.080)

⑥Top tape strength



The top tape requires a peel-off force of 0.1 to 0.7N in the direction of the arrow as illustrated below.

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RECTANGULAR FERRITE CHIP BEADS (HIGH CURRENT) FB series M type

1	Operating Temperature Range	

Specified Value -40°C~+85°C

2. Storage Temperature Range

Specified Value -40°C∼+85°C

[Test Methods and Remarks]

*Note: 0 to +40°C in taped packaging

3. Impedance

Specified Value Within the specified tolerance

[Test Methods and Remarks]

Measuring equipment : Impedance analyzer (HP4291A) or its equivalent Measuring frequency : 100 \pm 1 MHz

4. DC Resistance

Specified Value Within the specified range

[Test Methods and Remarks] Four-terminal method

Measuring equipment : Milliohm High-Tester 3226 (Hioki Denki) or its equivalent

5. Rated Current

Specified Value Within the specified range

6. Vibration

No significant abnormality Appearance Specified Value Impedance change: Within ±30% of the initial value

[Test Methods and Remarks] According to JIS C 0040.

Vibration type 2 hrs each in X,Y, and Z directions Total: 6 hr : 10 to 55 to 10Hz (/min.) : 1.5 mm (shall not exceed acceleration 196m/s²) Time Frequency range

Amplitude

Mounting method: Soldering onto PC board

7. Solderability

Specified Value 90% or more of immersed surface of terminal electrode shall be covered with fresh solder.

Test Methods and Remarks Solder temperature : 230±5°C : 4±1 sec. Immersion time Preconditioning

: Immersion into flux. Immersion and Removal speed: 25mm/sec

8. Resistance to Soldering Heat

: No significant abnormality Appearance Specified Value Impedance change: Within ±30% of the initial value

[Test Methods and Remarks]

150℃ for 3 min. 260±5℃ Preheating Resistance to Soldering Heat Duration 10±0.5 sec Preconditioning Immersion into flux. Immersion and Removal speed: 25mm/sec.

Recovery 2 to 3 hrs of recovery under the standard condition after the test.

9. Thermal Shock

Appearance : No significant abnormality Specified Value Impedance change: Within +50 % of the initial value

[Test Methods and Remarks] According to JIS C 0025. Conditions for 1 cycle

Step Temperature (°C) Duration (min.) 30±3 -40±3℃ 2 Room Temperature Within 3 3 85±2℃ 30±3 4 Room Temperature Within 3

Number of cycles: 100

Mounting method: Soldering onto PC board

Recovery: 2 to 3 hrs of recovery under the standard condition after the removal from test chamber.

10. Resistance to Humidity (steady state)

: No significant abnormality Specified Value Impedance change: Within ±30% of the initial value

[Test Methods and Remarks] Temperature : 40±2℃ Humidity 90 to 95% RH Duration 500^{+24}_{-0} hrs

Mounting method: Soldering onto PC board

Recovery : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber

11. Loading under Damp Heat

Appearances : No significant abnormality Specified Value Impedance change : Within $\pm 30\%$ of the initial value

[Test Methods and Remarks] Temperature: 40±2°C Humidity : 90 to 95%RH

Applied current : Rated current

Duration: 500+24 hrs

Mounting method : Soldering onto PC board

Recovery: 2 to 3hrs of recovery under the standard condition after the removal from test chamber

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RECTANGULAR FERRITE CHIP BEADS (HIGH CURRENT) FB series M type

12. High Temperature Loading Test

Appearance : No significant abnormality Impedance change : Within ±30% of the initial value Specified Value

[Test Methods and Remarks] Temperature : 85±2°C Duration: 500⁺²⁴₋₀ hrs Applied current: Rated current

Mounting method : Soldering onto PC board

Recovery : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber.

13. Bending Strength

Specified Value Appearance: No mechanical damage.

Test Methods and Remarks

Warp : 2mm
Testing board : Glass epoxy-resin substrate
Thickness : 0.8mm

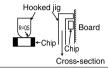
14. Adhesion of Electrode

Specified Value

No separation or indication of separation of electrode

[Test Methods and Remarks]

Applied force: 5N Duration: 10 sec.



Note on standard condition: "standard condition" referred to herein is defined as follows:

5 to 35°C of temperature, 45 to 85% relative humidity and 86 to 106kPa of air pressure.

When there are questions concerning measurement results: In order to provide correlation data, the test shall be conducted under condition of 20±2°C of temperature, 60 to 70% relative humidity and 86 to 106kPa of air pressure. Unless otherwise specified, all the tests are conducted under the "standard condition."

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FBM Type

1. Circuit Design

Precautions

Operating environment

1. The products described in this specification are intended for use in general electronic equipment, (office supply equipment, telecommunications systems, measuring equipment, and household equipment). They are not intended for use in mission-critical equipment or systems requiring special quality and high reliability (traffic systems, safety equipment, aerospace systems, nuclear control systems and medical equipment including life-support systems,) where product failure might result in loss of life, injury or damage. For such uses, contact TAIYO YUDEN Sales Department in advance

◆Rated current

1. Rated current of this product is shown in this catalogue, but please be sure to have the base board designed with adequate inspection in case of the generation of heat becomes high within the rated current range when the base board is in high resistance or in bad heating conditions.

2. PCB Design

Precautions

◆Land pattern design

Please refer to a recommended land pattern.

3. Considerations for automatic placement

Adjustment of mounting machine

1. Excessive impact load should not be imposed on the products when mounting onto the PC boards 2. Mounting and soldering conditions should be checked beforehand.

Technical considerations

Precautions

Adjustment of mounting machine

1. When installing products, care should be taken not to apply distortion stress as it may deform the products.

4. Soldering

Precautions

◆Wave soldering

1. Please refer to the specifications in the catalog for a wave soldering.

Reflow soldering

1. Please contact any of our offices for a reflow soldering, and refer to the recommended condition specified.

◆Lead free soldering

1. When using products with lead free soldering, we request to use them after confirming adhesion, temperature of resistance to soldering heat, etc. sufficiently

Preheating when soldering Heating: The temperature difference between soldering and remaining heat should not be greater than 150°C.

Cooling: The temperature difference between the components and cleaning process should not be greater than 100°C. ecommended conditions for using a soldering iron

Put the soldering iron on the land-pattern

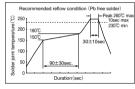
Soldering iron's temperature - Below 350°C Duration - 3 seconds or less

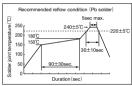
The soldering iron should not directly touch the inductor.

◆Wave, Reflow, Lead free soldering

1. If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products.

Technical considerations





Preheating when soldering 1. There is a case that products get damaged by a heat shock

Recommended conditions for using a soldering iron

1. If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products

5. Handling

Handling
 Keep the inductors away from all magnets and magnetic objects.

♦Setting PC boards

1. When setting a chip mounted base board, please make sure that there is no residual stress to the chip by distortion in the board or at screw part.

◆Breakaway PC boards (splitting along perforations) Precautions

1. When splitting the PC board after mounting inductors, care should be taken not to give any stresses of deflection or twisting to the board. 2. Board separation should not be done manually, but by using the appropriate devices.

Mechanical considerations

1. Please do not give the inductors any excessive mechanical shocks

Handling 1. There is a case that a characteristic varies with magnetic influence.

◆Setting PC boards 1. There is a case that a characteristic varies with residual stress.

Technical consider-

Breakaway PC boards (splitting along perforations)

1. There is a case to be damaged by a mechanical shock

Planning pattern configurations and the position of products should be carefully performed to minimize stress.
 Mechanical considerations

6. Storage conditions

◆Storage

1. To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled · Recommended conditions

Precautions

0~40°C Ambient temperature Below 70% RH Humidity

The ambient temperature must be kept below 30°C. Even under ideal storage conditions, solderability of products electrodes may decrease as time passes For this reason, inductors should be used within 6 months from the time of delivery

considerations

ations

Technical

1. Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place

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